**Operation:** SMT+DIP 式 SMT& 3.1Type-C 插座

Halogen Free | LEAD FREE | RoHS Compliant

**ITEM NO.:MC-313D** (Consumer Electronics)

(9.85L×9.64W×3.16H & DUL SMT LOW PCB TYPE)

**MEMORY-CARD-SOCKETS**

## Technical parameter

| PROJECT \ LEVEL | | A[better product] | B[average product] |
|---|---|---|---|
| Electrical Properties | Contact Rating | 3A, 24V DC | |
| | Initial Contact Resistance | 30mΩ max. | 50mΩ max. |
| | Insulation Resistance | 100MΩ min.500V DC | Skey/PD：100MΩ min.300V DC |
| | Withstand Voltage | 500V AC for 1 minute | 350 V AC for 1 minut |
| Durable Performance | There No Load | 6,500 Cycles | 5,500 Cycles |
| | Rated Load | 5,500 Cycles | 4,500 Cycles |
| Sterage temp. | | -25℃～+75℃(Operating Temp: ) | |

外焊 SMT+DIP

侧向導入 LATERAL

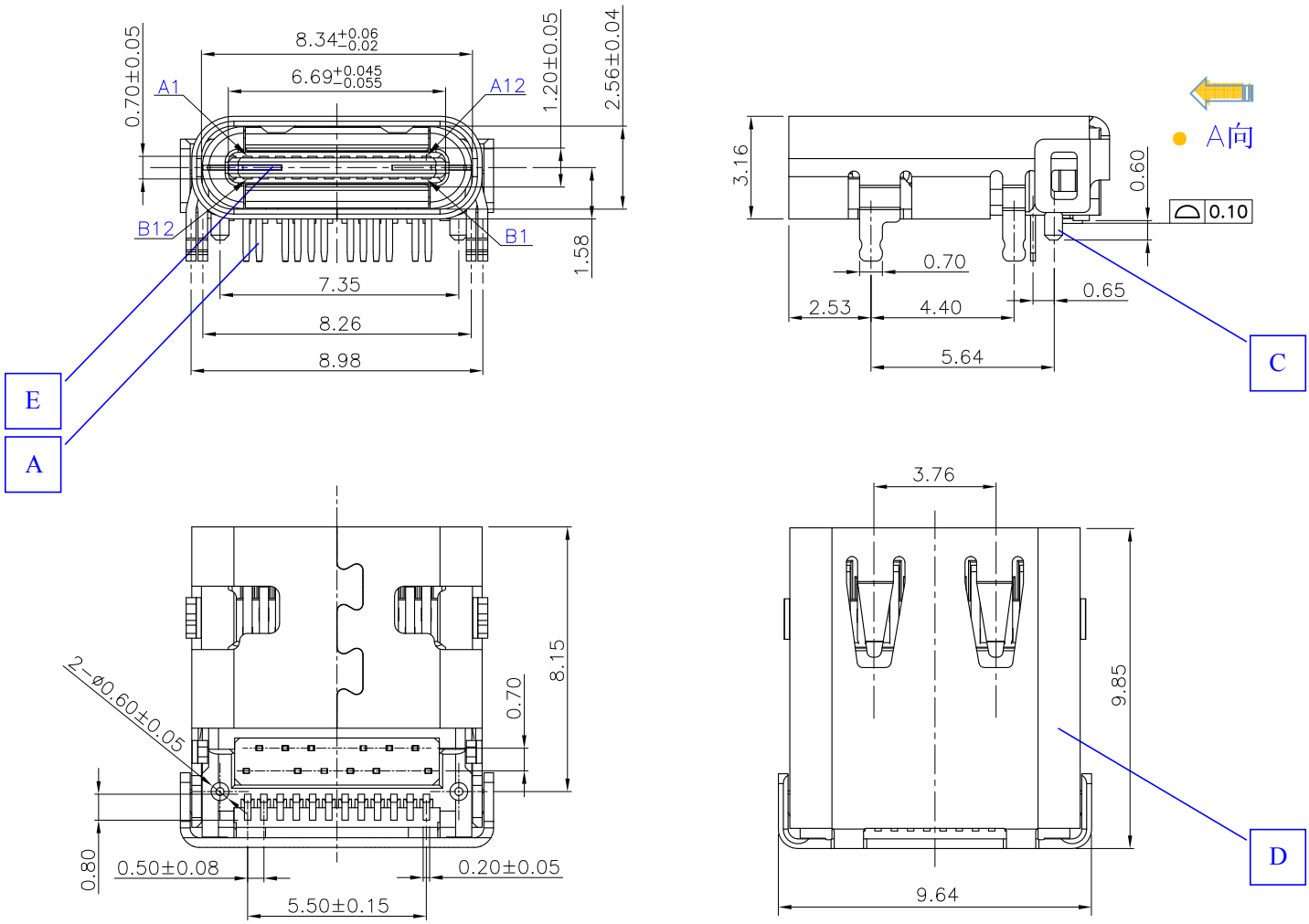
精密部品 NICETY

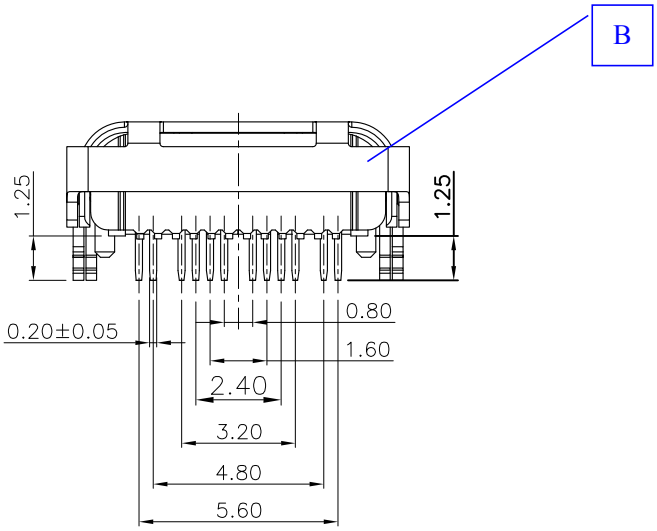
可靠 STABILIZE

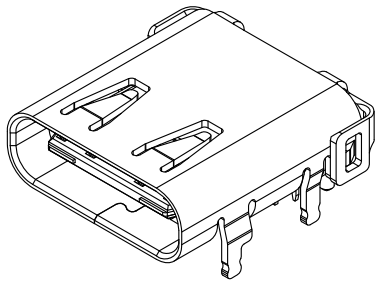
環保材质 RoHS

Page1

Unit:mm





● A向示意图

## SPECIFED TOLERANCES

UNLESS OTHERWISE

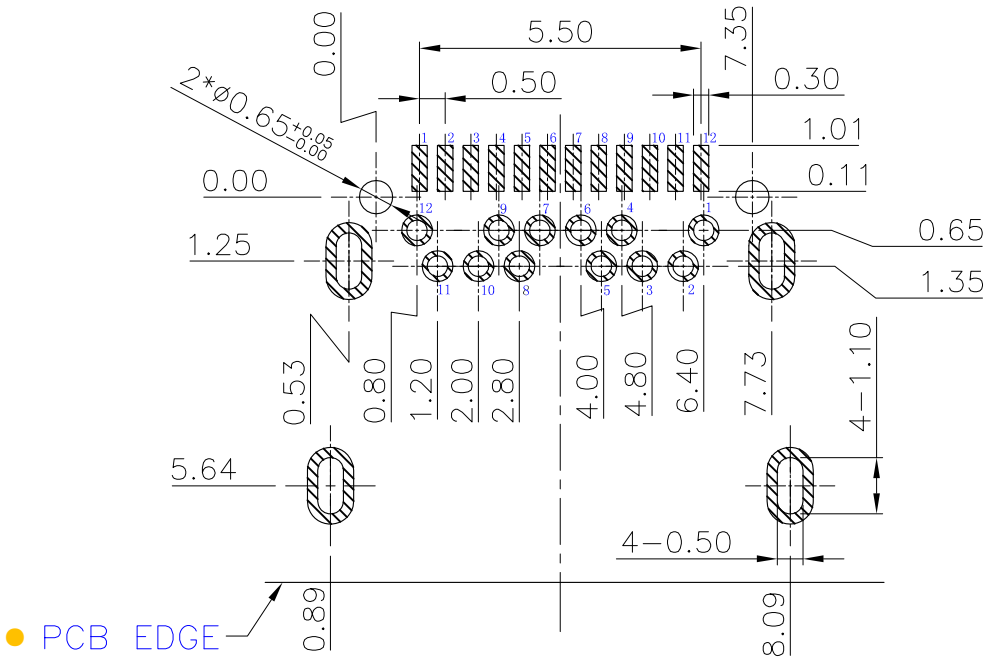
| DECIMALS | ANGLES |
|---|---|
| X.X :±0.25 | X.X :±3° |
| X.XX :±0.15 | X.XX :±2° |
| X.XXX :±0.10 | |

| Material declaration | | | |
|---|---|---|---|
| **No.** | **NAME** | **MATERIAL** | **DESCRIPTION** |
| ① A | TERMINAL<br>接触端子 | COPPER ALLOY【G/F】 | 2.0 μ m Ni PLATED OVERALL;<br>0.25 μ m Au PLATED CONTACT AREA;<br>GOLD FLASH ON SOLDER AREA. |
| ② B | SHIELDING PLATE 屏蔽壳 | STAINLESS【G/F】 | 0.25 μ m Ni PLATED OVERALL; |
| ③ C | CASE | THERMOPLASTIC | UL 94V-0,COLOR:BLACK; |
| ④ D | SHELL | STAINLESS【G/F】 | 0.25 μ m Ni PLATED OVERALL; |
| ⑤ E | GUARD PLATE | STAINLESS【G/F】 | STAINLESS STEEL(t=0.10mm) |

## MATERIAL

# CIRCUIT BOARD SIZE
(Vertical view)

| | | |
|---|---|---|
| **Operating Force** | Inward | 8.0～20.0N.(1N.=100gram-force) |
| | Exiting | 6.0～20.0N.(1N.=100gram-force)MIN |




## PIN ASSIGNMENTS

| PIN | Signal NAME | Description | PIN | Signal NAME | Description |
|---|---|---|---|---|---|
| A1 | GND | Ground return | B12 | GND | Ground return |
| A2 | SSTXp1 | Positive half of firs SuperSpeed TX differential pair | B11 | SSRXp1 | Positive half of second SuperSpeed RX differential pair |
| A3 | SSTXn1 | Negatice half of first SuperSpeed TX differential pair | B10 | SSRXn1 | Negative half of second SuperSpeed RX differential pair |
| A4 | V BUS | Bus Power | B9 | V BUS | Bus Power |
| A5 | CC1 | Configuration Channel | B8 | SBU2 | Sideband Use(SBU) |
| A6 | Dp1 | Positive half of the USB 2.0 differential pair-Position 1 | B7 | Dn2 | Negative half of the USB 2.0 differential pair-Position 2 |
| A7 | Dn1 | Negative half of the USB 2.0 differential pair-Position 1 | B6 | Dp2 | Positive half of the USB 2.0 differential pair-Position 2 |
| A8 | SBU1 | Sideband Use(SBU) | B5 | CC2 | Configuration Channel |
| A9 | V BUS | Bus Power | B4 | V BUS | Bus Power |
| A10 | SSRXn2 | Negative half of second SuperSpeed RX differential pair | B3 | SSTXn2 | Negatice half of first SuperSpeed TX differential pair2 |
| A11 | SSRXp2 | Positive half of second SuperSpeed RX differential pair | B2 | SSTXp2 | Positive half of firs SuperSpeed TX differential pair2 |
| A12 | GND | Ground return | B1 | GND | Ground return |

## 注記 NOTICE

1. 碩方公司擁有最終解釋權；The SOFNG company reserves the right of final interpretation；
2. 文件禁止外洩、轉載；Leaked and reproduced prohibited；
3. 未經授權修改無效。Modify is invalid.